Claims

[Claim 1]

A packaged wheat flour, comprising a wheat flour packed in a shaker-type container having one or more shaker holes having a maximum width of 2 to 20 mm, the wheat flour having an angle of repose of 25 to 54 degrees, wherein the wheat flour has a mean particle diameter of 40 to 200 μm.

[Claim 2]

The packaged wheat flour according to claim 1, wherein the shaker-type container has 2 to 9 shaker holes.

[Claim 3]

The packaged wheat flour according to claim 1 or 2, wherein the wheat flour is a granulated wheat flour or a mixture of a granulated wheat flour and a non-granulated wheat flour.

[Claim 4]

The packaged wheat flour according to any one of claims 1 to 3, wherein the angle of repose of the wheat flour is 40 to 51 degrees.

[Claim 5]

The packaged wheat flour according to any one of claims 1 to 4, wherein the wheat flour is a soft wheat flour.

[Claim 6]

A method of applying a wheat flour, comprising shaking out a wheat flour through shaker holes to apply the wheat flour to an object, wherein the wheat flour is packed in a shaker-type container having 2 to 9 shaker holes having a maximum width of 2 to 20 mm, and the wheat flour has an angle of repose of 25 to 54 degrees, wherein the wheat flour has a mean particle diameter of 40 to 200 μm.

[Claim 7]

A method of suppressing scattering and formation of lumps of a wheat flour, comprising shaking out a wheat flour through shaker holes to apply the wheat flour to an object, wherein the wheat flour is packed in a shaker-type container having 2 to 9 shaker holes having a maximum width of 2 to 20 mm, and the wheat flour has an angle of repose of 25 to 54 degrees, wherein the wheat flour has a mean particle diameter of 40 to 200 μm.

[Claim 8]

The method according to claim 6 or 7, wherein the wheat flour is a granulated wheat flour or a mixture of a granulated wheat flour and a non-granulated wheat flour.

[Claim 9]

The method according to any one of claims 6 to 8, wherein the wheat flour is a soft wheat flour.